

August 2009
SupreMOS^M

FCP11N60N / FCPF11N60NT

N-Channel MOSFET 600V, 10.8A, 0.299 Ω

Features

- $R_{DS(on)}$ = 0.255 Ω (Typ.)@ V_{GS} = 10V, I_D = 5.4A
- Ultra Low Gate Charge (Typ. Qg = 27.4nC)
- · Low Effective Output Capacitance
- · 100% Avalanche Tested
- · RoHS Compliant



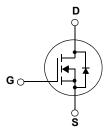
Description

The SupreMOS MOSFET, Fairchild's next generation of high voltage super-junction MOSFETs, employs a deep trench filling process that differentiates it from preceding multi-epi based technologies. By utilizing this advanced technology and precise process control, SupreMOS provides world class Rsp, superior switching performance and ruggedness.

This SupreMOS MOSFET fits the industry's AC-DC SMPS requirements for PFC, server/telecom power, FPD TV power, ATX power, and industrial power applications.







MOSFET Maximum Ratings T_C = 25°C unless otherwise noted*

Symbol		Parameter		FCP11N60N	FCPF11N60NT	Units	
V _{DSS}	Drain to Source Voltage			(V		
V _{GSS}	Gate to Source Voltage			:	±30	V	
1	Drain Current	-Continuous (T _C = 25°C)		10.8	10.8*		
ID	Drain Current	-Continuous (T _C = 100°C)		6.8	6.8*	Α	
I _{DM}	Drain Current	- Pulsed	(Note 1)	32.4	32.4*	Α	
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		2) 201.7		mJ		
I _{AR}	Avalanche Current		3.7		Α		
E _{AR}	Repetitive Avalanche Energy			0.94		mJ	
dv/dt	MOSFET dv/dt Ruggedness	1		100		V/ns	
uv/ut	Peak Diode Recovery dv/dt		(Note 3)	3) 20		V/ns	
D	Dower Dissination	(T _C = 25°C)		94.0	32.1	W	
P_{D}	Power Dissipation	- Derate above 25°C		0.75	0.26	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range -55 to +150		°С				
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds				°C		

^{*}Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter F		FCPF11N60NT	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.33	3.9	
R_{\thetaCS}	Thermal Resistance, Case to Heat Sink (Typical)		0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	62.5	

查询"FCP11N60N"供应商 Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCP11N60N	FCP11N60N	TO-220	-	-	50
FCPF11N60NT	FCPF11N60NT	TO-220F	-	-	50

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 1 \text{mA}, V_{GS} = 0 \text{V}, T_C = 25^{\circ} \text{C}$	600	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 1mA, Referenced to 25°C	-	0.73	-	V/°C
	Zero Gate Voltage Drain Current	V _{DS} = 480V, V _{GS} = 0V	-	-	10	
IDSS	Zero Gate Voltage Drain Current	$V_{DS} = 480V, V_{GS} = 0V, T_{C} = 125^{\circ}C$	-	-	100	μ Α
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.0	1	4.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10V, I _D = 5.4A	-	0.255	0.299	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40V, I_{D} = 5.4A$	-	13.5	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	\(- 400\(\) \(- 0\(\)	-	1130	1505	pF
C _{oss}	Output Capacitance	V _{DS} = 100V, V _{GS} = 0V f = 1MHz	-	45	60	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1111112	-	3	5	pF
C _{oss}	Output Capacitance	$V_{DS} = 380V, V_{GS} = 0V, f = 1MHz$	-	25	-	pF
C _{oss} eff.	Effective Output Capacitance	V_{DS} = 0V to 480V, V_{GS} = 0V	-	130	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		-	27.4	35.6	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DS} = 380V, I_{D} = 5.4A,$	-	4.9	-	nC
Q _{gd}	Gate to Drain "Miller" Charge	$V_{GS} = 10V$ (Note 4)	-	8.8	-	nC
ESR	Equivalent Series Resistance (G-S)	Drain Open		2.0		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		-	13.6	37.2	ns
t _r		$V_{DD} = 380V, I_{D} = 5.4A$	-	9.1	28.2	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 4.7\Omega$	-	42.0	94.0	ns
t _f	Turn-Off Fall Time	(Note 4)	-	10.0	30.0	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current			-	10.8	Α
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	32.4	Α
V_{SD}	Drain to Source Diode Forward Voltage $V_{GS} = 0V$, $I_{SD} = 5.4A$		-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _{SD} = 5.4A	-	268	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	3.1	-	μС

- Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} = 3.7A, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C
- 3. $I_{SD} \leq$ 10.8A, di/dt \leq 200A/ μ s, V_{DD} = 380V, Starting T_J = 25°C
- 4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

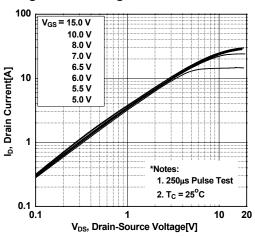


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

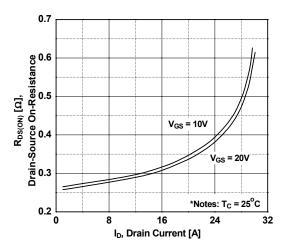


Figure 5. Capacitance Characteristics

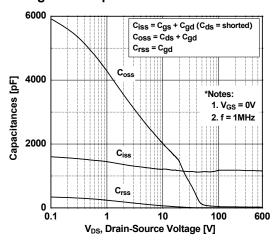


Figure 2. Transfer Characteristics

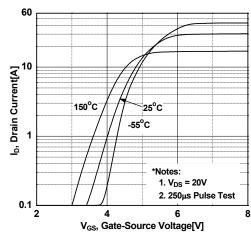


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

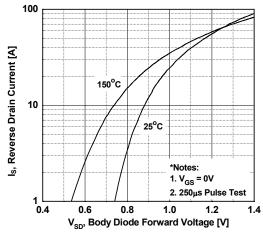
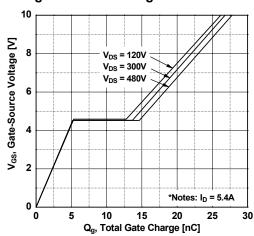


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

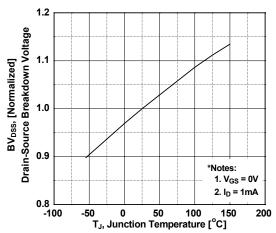


Figure 9. Maximum Safe Operating Area FCP11N60N

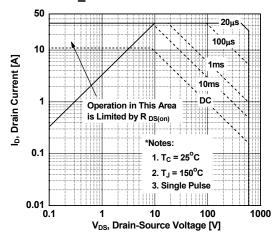


Figure 11. Maximum Drain Current vs. Case Temperature

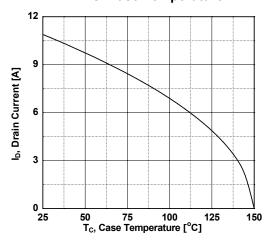


Figure 8. On-Resistance Variation vs. Temperature

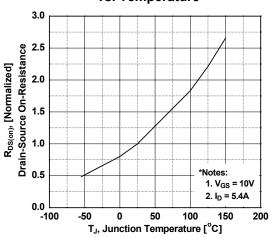
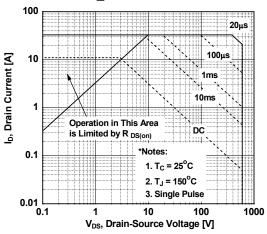


Figure 10. Maximum Safe Operating Area _ FCPF11N60NT



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve _ FCP11N60N

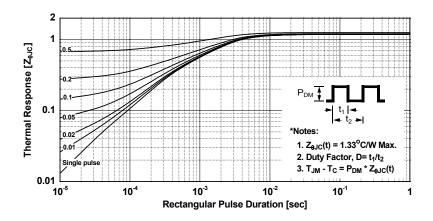
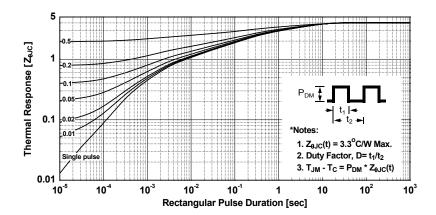
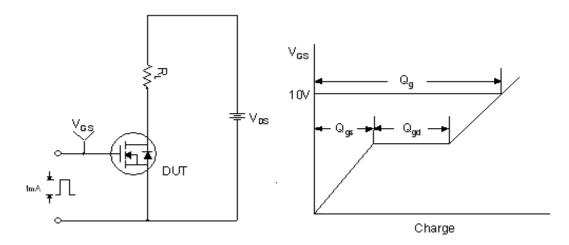


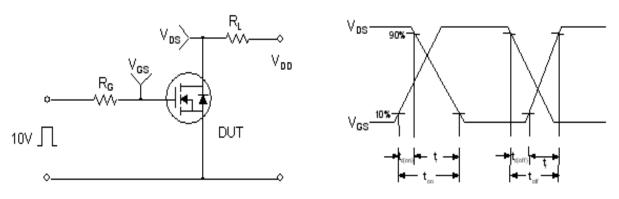
Figure 13. Transient Thermal Response Curve _ FCPF11N60NT



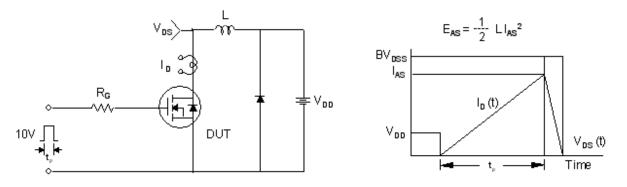
Gate Charge Test Circuit & Waveform



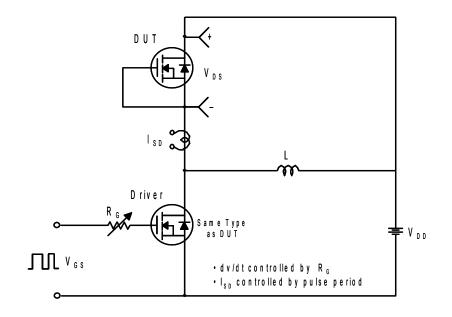
Resistive Switching Test Circuit & Waveforms

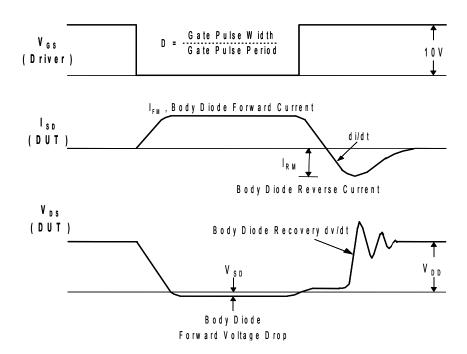


Unclamped Inductive Switching Test Circuit & Waveforms



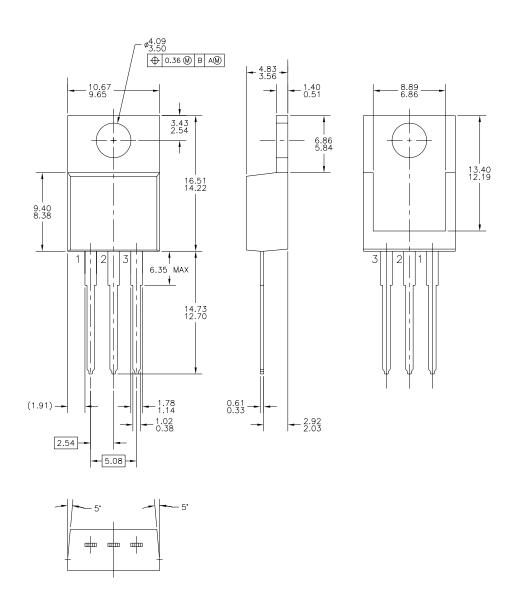
Peak Diode Recovery dv/dt Test Circuit & Waveforms





查询"FCP11N60N"供应商 Mechanical Dimensions

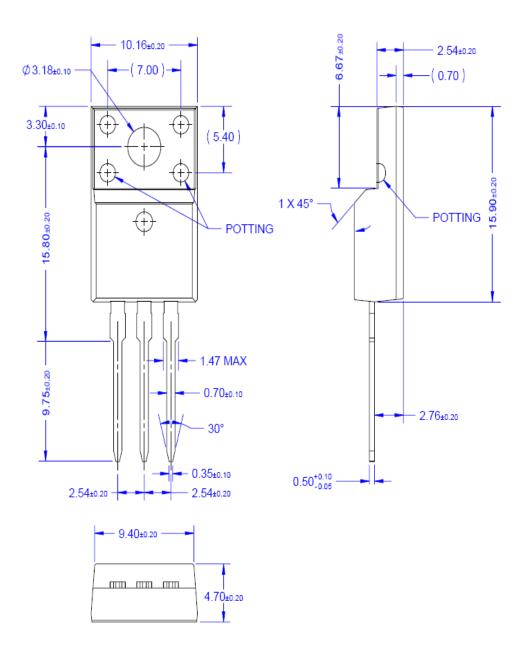
TO-220



Dimensions in Millimeters

Mechanical Dimensions

TO-220F



Dimensions in Millimeters





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